L Number	Hits	Search Text	DB	Time stamp
1	3270	257/676	USPAT;	2004/09/17 18:58
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
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2	13659	(semiconductor or die or chip or IC) and	USPAT;	2004/09/17 18:39
		(align\$4 or reference) near line	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	1868	((semiconductor or die or chip or IC) and	USPAT;	2004/09/17 18:42
		(align\$4 or reference) near line) and	US-PGPUB;	
		(mold\$3 or encapsulat\$3)	EPO; JPO;	
		• • • •	DERWENT;	
			IBM TDB	
4	1097	257/782	USPĀT;	2004/09/17 20:23
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
5	1		USPAT	2004/09/17 19:48
6	1	•	USPAT	2004/09/17 19:48
7	1		USPAT	2004/09/17 19:48
8	1062	257/797	USPAT;	2004/09/17 20:46
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
9	1		USPĀT	2004/09/17 20:29
10	1		USPAT	2004/09/17 20:30
11	1684	257/783	USPAT;	2004/09/17 21:43
			US-PGPUB;	
			EPO; JPO;	
]			DERWENT;	
			IBM_TDB	
12	4690	257/787	USPAT;	2004/09/17 22:18
			US-PGPUB;	
			EPO; JPO;	,
			DERWENT;	
			IBM_TDB	
13	2539	257/777	USPAT;	2004/09/17 22:19
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	